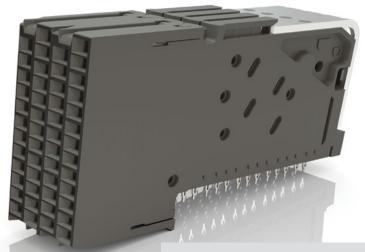


# HIGH-DENSITY BACKPLANE HEADERS & SOCKETS

(1.80 mm) .071" PITCH







#### **FEATURES & BENEFITS**

- Small form factor and modular design provides significant space-savings and flexibility
- High-performance system
- Up to 84 differential pairs per linear inch
- 3, 4 and 6-pair designs on 4, 6 and 8 columns
- Integrated power, guidance, keying and end walls available
- 85  $\Omega$  and 100  $\Omega$  options
- Combine any configuration of modules to create one integrated receptacle (BSP Series); corresponding terminal modules are individually mounted to the backplane
- Press-fit extraction and insertion tool options; please visit samtec.com/tooling for details

#### **MODULAR DESIGN**



Signal, Power & Keying / Guidance options can be customized in any configuration

#### HIGH-DENSITY, SMALL FORM FACTOR



(Both shown with six 4-pair, 8 column receptacles)

#### XCede® HD

Up to 84 pairs per linear inch

# Traditional Backplane

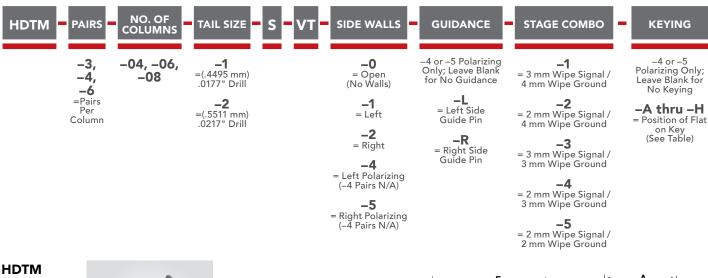
Up to 76 pairs per linear inch

#### **KEY SPECIFICATIONS**

PITCH	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE
1.80 mm	LCP	Phosphor Bronze (HDTM Series) Copper Alloy (HDTF & HPTS Series)	Au or Sn over 50 μ" (1.27 μm) Ni	-40 °C to + 105 °C (HDTX Series)

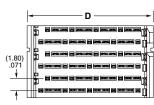


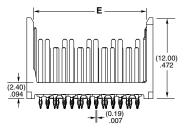
### (1.80 mm) .071" PITCH • HIGH-DENSITY BACKPLANE HEADER

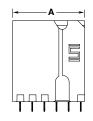


HDTM Board Mates: HDTF, BSP (See HDTF for more information.)









HDTM-4-06-1-S-VT-0-1 SHOWN

NO. OF		Α	С		
COLUMNS	No Walls	Left Wall	Right Wall	Left Polarize	Right Polarize
-04	(7.06) .278	(8.20) .322	(8.06) .317	N/A	N/A
-06	(10.66) .420	(11.80) .465	(11.66) .459	(17.14) .675	(16.65) .656
-08	(14.26) .561	(15.40) .606	(15.26) .600	(20.74) .817	(20.25) .797

(16.75) .659

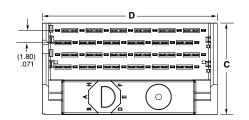
(23.95) .943

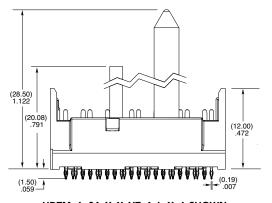
-08	(14.26) .561 (15.40	)) .606 (15.26) .600	(20.74) .817	
			l	
<b>PAIRS PER</b>	D	E		
COLUMN	Standard Wall	-		
-03	(15.10) .594	(13.15) .518		

(18.70) .736

(25.90) 1.020

KEYING								
	-A	-В	-c	-D	-E	-F	-G	-Н
-L / -R	A B C D	A B C B	A B C D	A G F E	$A \bigcup_{B}^{H} \bigcup_{C}^{G} E$	A = G = G $C = G$	A B C D	A = G = G $B = G$ $C = G$





HDTM-6-04-X-X-VT-4-L-X-A SHOWN

View complete specifications at: samtec.com?HDTM

#### Notes

Some lengths, styles and options are non-standard, non-returnable. XCede® is a registered trademark of Amphenol.

-04

-06

## **Mouser Electronics**

**Authorized Distributor** 

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## Samtec:

HDTM-3-04-1-S-VT-0-1 HDTM-3-06-1-S-VT-0-1 HDTM-3-08-1-S-VT-0-1 HDTM-4-04-1-S-VT-0-1 HDTM-4-06-1-S
VT-0-1 HDTM-4-08-1-S-VT-0-1 HDTM-3-04-1-S-VT-0-2 HDTM-3-04-2-S-VT-0-4 HDTM-3-06-1-S-VT-0-2 HDTM-3-06
2-S-VT-0-3 HDTM-3-08-1-S-VT-0-2 HDTM-3-08-2-S-VT-0-4 HDTM-6-04-1-S-VT-0-1 HDTM-6-06-1-S-VT-0-1 HDTM-6-06-1-S-VT-0-2 HDTM-6-08-1-S-VT-0-2